

Remarks

Claims 4, 6, and 7 have been rejected under 35 U.S.C. § 112, second paragraph as being indefinite. These claims have been amended to overcome this rejection. Thus, withdrawal of this rejection is respectfully requested.

Claims 1, 3, 5, and 7 have been rejected under 35 U.S.C. § 102(b) as being anticipated by McShane, U.S. Patent No. 5,012,386. Claim 2 has been rejected under 35 U.S.C. § 103(a) as being unpatentable in view of McShane, U.S. Patent No. 5,012,386. Claims 1, 3, 5, 6, and 7 have been rejected under 35 U.S.C. § 102(b) as being anticipated by Budde, U.S. Patent No. 3,825,803. These rejections are overcome for the reasons set forth below.

Applicants' invention, as recited in amended claim 1, includes a feature that is neither disclosed nor suggested by the cited art, namely:

...the chip carrier adapted to hold an integrated circuit and adapted to have the integrated circuit removed therefrom (emphasis added).

McShane does not disclose a chip carrier but discloses an electronic package for permanently mounting the integrated circuit. Similarly, Budde is directed to a structure for permanently mounting an integrated circuit. In contrast, the invention of claim 1 is directed to a chip carrier adapted so that the integrated circuit may be removed. In this way, the chip carrier may be used to transport and protect the integrated circuit. Subsequently, the integrated circuit may be removed from the chip carrier so that it can be, for example, mounted on a printed circuit board. Thus, claim 1 is distinguished from the cited art, alone or in combination. Claims 2-7 depend from claim 1 and, therefore, are also distinguished from the cited art. Thus, withdrawal of these rejections is respectfully requested.

Applicants have added new claims 21-28. Claim 21 recites:

...wherein the second well has a base, the leads positioned above the base and below the upper surface.

Claim 22 recites:

...wherein the base, the first well, and the outer well form an integrated circuit carrier and the chip carrier further comprises a plurality of integrated circuit carriers.

Claim 23 recites:

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...a cover adapted to hold an integrated circuit in the chip carrier.

Claims 24 recites:

...a cover for holding an integrated circuit in the chip carrier.

Claim 25 recites:

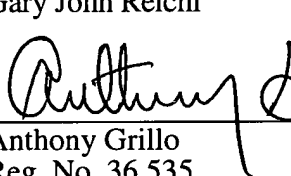
...the chip carrier adapted to temporarily hold an integrated circuit.

Each of these claims recites further structure of the chip carrier as a device suitable for transporting an integrated circuit. The cited art does not disclose these features. Thus, claims 21-25 area allowable. Claims 26-28 depend from claim 25.

Based on the forgoing, the above-identified application is in condition for allowance.

Respectfully Submitted,

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